

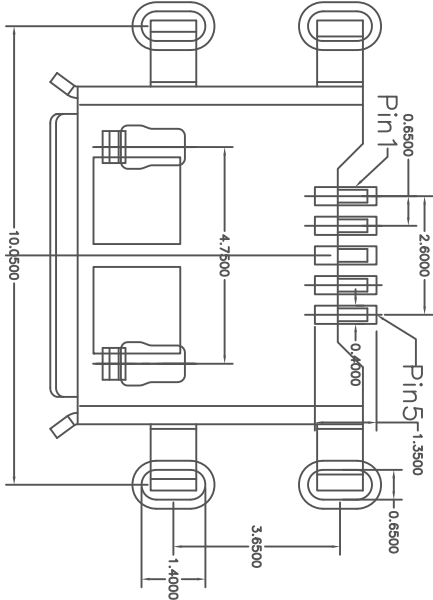
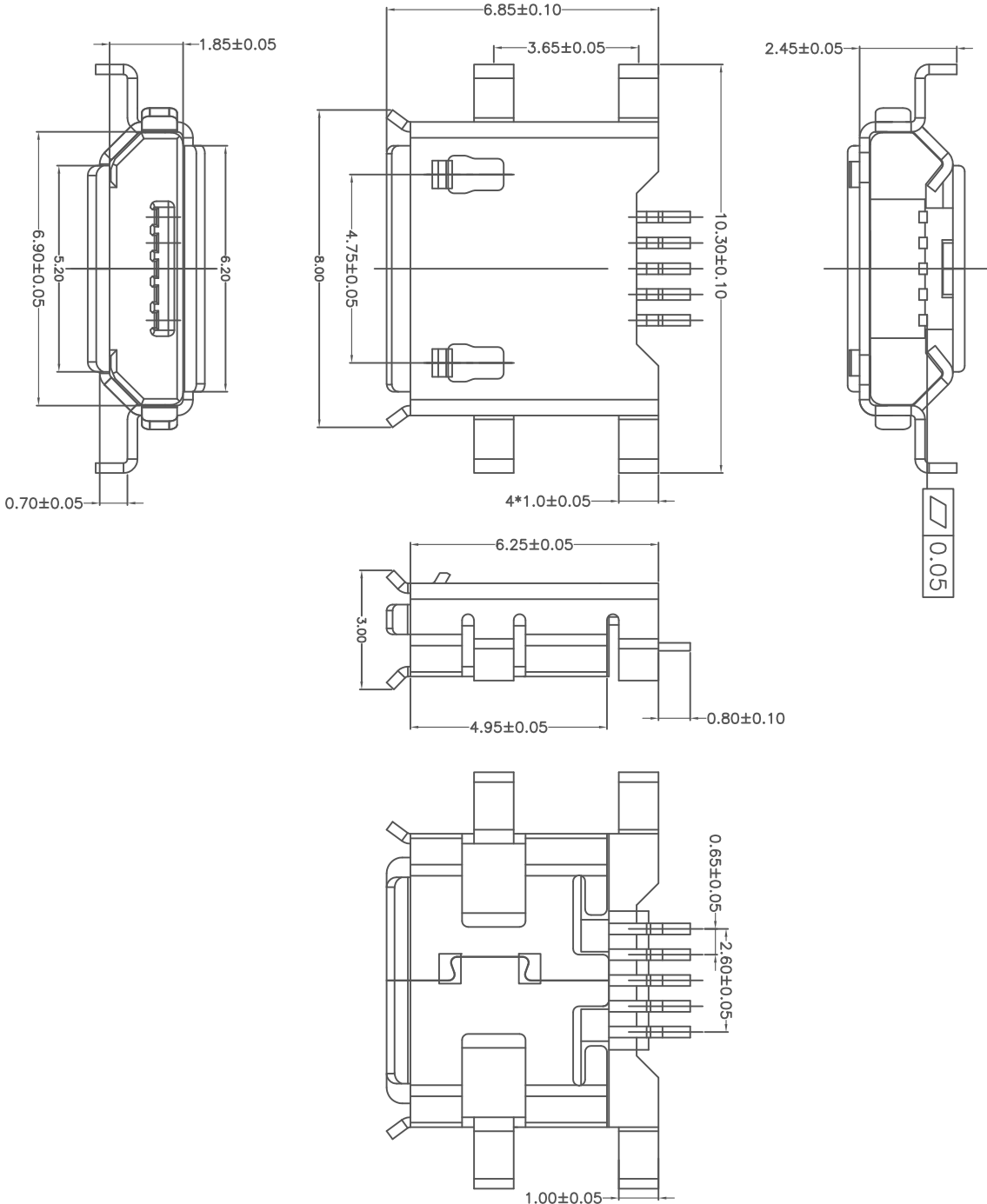
Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy, t=0.20mm
- 1.3 Shell: copper alloy, t=0.25mm

2. Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 KgF Max.
- 2.6 Total unmating force: 1.0 KgF Min. 0.81~2.05 KgF Min. after 10000 insertion/extraction cycles
- 2.7 Temperature range: -30° C~80° C



RECOMMENDED PCB LAYOUT

UNIT:MM		TYPE:		MODEL NO:		PAGE 1 OF 1	
DESIGNER BY: Zhuyin		Micro USB B Type 5Pin SMT 沉板 0.7 帶 1.0 插板		HUSM-005-RFS-20		SCALE VER	
CHECK BY: Shiron		2014/4/23		PAPER NO: A4		B	
APPROVED BY: Jason		2014/4/23		IF TECHNOLOGY, INC.			
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